

CLAIMS

1. An inspecting device equipped with:
 - a performance substrate provided with a terminal for
5 inspection;
 - a contactor substrate provided with a probe contacting
an object to be inspected; and
 - a probe card,
wherein said probe card is a multi-layered substrate in
10 which a resin thin film is laminated on a ceramic board.
2. An inspecting device equipped with:
 - a performance substrate provided with a terminal for
inspection;
 - 15 a contactor substrate provided with a probe contacting
an object to be inspected; and
 - a probe card intervening between said probe of said
contactor substrate and said terminal of said performance
substrate,
 - 20 wherein said probe card is a multi-layered substrate in
which a resin thin film is laminated on a ceramic board.
3. An inspecting device equipped with:
 - a performance substrate provided with a terminal for
25 inspection;
 - a contactor substrate provided with said probe contacting
an object to be inspected; and
 - a probe card electrically connected to said probe of said
contactor substrate,
 - 30 said inspecting device being constituted such that the
object to be inspected is placed between said performance
substrate and said probe card,
wherein said probe card is a multi-layered substrate in
which a resin thin film is laminated on a ceramic board.

4. The inspecting device according to any of claims 1 to 3,
wherein the ceramic board of said probe card comprises
non-oxide ceramic.
- 5 5. The inspecting device according to any of claims 1 to 4,
wherein said resin thin film comprises thermosetting
resin.
6. A probe card for the use of inspecting integrated circuits
10 formed on a semiconductor-wafer,
a resin insulating layer and a conductor circuit are
serially formed in alternate fashion and in repetition on a
ceramic board.
- 15 7. The probe card according to claim 6,
wherein a conductor-filled through hole is formed in said
ceramic board.
8. The probe card according to claim 6 or 7,
20 wherein the resultant conductor circuits formed through
said resin layer are interconnected each other by a via hole.
9. The probe card according to any of claims 6 to 8,
wherein said ceramic board comprises non-oxide ceramic.
- 25 10. The probe card according to any of claims 6 to 9,
wherein said resin layer comprises thermosetting resin.
11. The probe card according to any of claims 6 to 10,
30 wherein said ceramic board is in a disc shape.
12. The probe card according to any of claims 6 to 11,
wherein said resin layer is formed so as to cover the whole
of at least one of main faces of said ceramic board.